

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t6656bidc-3.3#trpbf

(Engineering Calculation)

DFN 2mm X 2mm Exp. Pad

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**TOTAL MASS (g) : 0.00911**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000567	1000000	62237.078125		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.002935	975000	322161.9375		
		Iron (Fe)	7439-89-6	0.000072	24000	7903.12158203		
		Phosphorus (P)	7723-14-0	0.000001	300	109.765571594		
		Zinc (Zn)	7440-66-6	0.000002	700	219.531143188		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.003010</b>	<b>1000000</b>	<b>330394.34375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000136	1000000	14963.7695312		
		<b>External Plating Total:</b>				<b>0.000136</b>	<b>1000000</b>	<b>14963.7695312</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000072	1000000	7903.12158203		
		<b>Internal Plating Total:</b>				<b>0.000072</b>	<b>1000000</b>	<b>7903.12158203</b>
Die Attach	ELECTRICALLY INSULATING ADHESIVE	Silver (Ag)	7440-22-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000005	50000	548.827819824		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000027	300000	2963.67041016		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000059	650000	6476.16845703		
<b>Die Attach Total:</b>				<b>0.000091</b>	<b>1000000</b>	<b>9988.66699219</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000677	130000	74311.2890625		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.004481	860000	491859.5		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000052	10000	5707.80957031		
		<b>Encapsulation Total:</b>				<b>0.005210</b>	<b>1000000</b>	<b>571878.625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000024	1000000	2634.3737793		
					<b>TOTAL MASS (g) :</b>	<b>0.00911</b>		